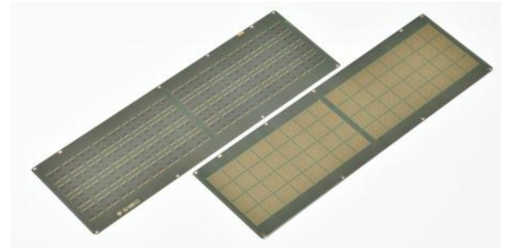
Plastic BGA Substrate

Features

■ Plastic BGA Substrate

SHINKO provides organic substrates using prepreg for BGA packages in logic, memory, and sensor devices, etc.

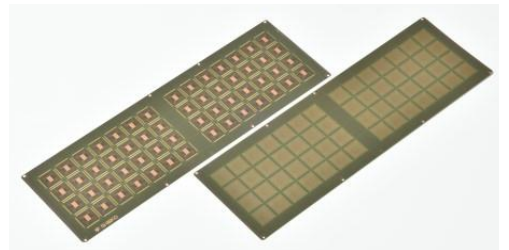


- **2 Layers / 4 Layers Substrate with Through Hole**
  - Substrate with low cost and high reliability
  - Superior electrical characteristics
- **Build-up Substrate ~IVH*~**
  - Thinner substrate thickness is available by using thin core. (*ex.* less than 150μm total thickness with 4 layers)
  - Multilayer structure consisting of 4 or more layers is possible.
  - Available for both WB (Wire Bonding) and FC (Flip-Chip)
  - High density is possible by using semi-additive process and laser vias.
  - Structure of via on PTH (Plated Through Hole) and structure of stacked via are supported.

*IVH : Interstitial Via Hole

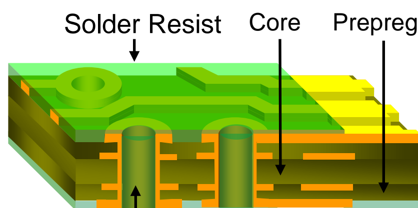
■ Plastic BGA Coreless Substrate ~IVH3~

SHINKO provides coreless substrate using IVH technology for improving performance in a thinner form factor.

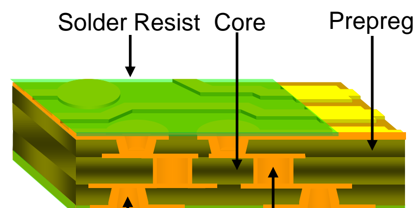


- Ultimate substrate thickness reduction is possible by removing core layer. (*ex.* 80μm or less total thickness with 3 layers)
- Superior electrical characteristics
- Multilayer structure consisting of 3 or more layers is possible.
- Available for both WB (Wire Bonding) and FC (Flip-Chip) interconnect
- High density is possible by using semi-additive process and laser vias.
- Structure of stacked via is supported.

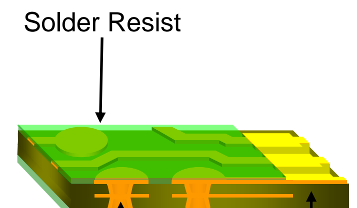
Structure



4 Layers Substrate with Through Hole



4 Layers IVH



3 Layers IVH3

SHINKO ELECTRIC INDUSTRIES CO., LTD.
80 Oshimada-machi, Nagano-shi, Nagano 381-2287 JAPAN

SHINKO

Please contact us via inquiry form on the web.
https://www.shinko.co.jp/english/product/inquiry/form/index.php

© 2023 SHINKO ELECTRIC INDUSTRIES CO., LTD.